I think these are the modifications needed to WMS:

* Amend SKU master to add a column for “PIP” (parts individual packaging)
* Add module/option to print picklist at pick-line level
* Add column on picklist to print PIP (per order line, based on the SKU)
* Add module to print label which will be pasted on the loose individual packaging tiny box (at the lease: SKU, order #, order line #), see similar sample from Sony Corp warehouse (attached)

Can you check if this is feasible at first glance? Will need to go-live ideally end-Feb for S/P migration (or even better if earlier, so it can support the Japan Unique S/P in end-Jan)

And if this was discussed in the initial IT workshops? Else Sony engineering/Matsubara asks how much it will cost to modify our system



Requirements for the label (the one highlighted in yellow in previous email)

* Sony logo
* Repair part number (PN)
* PN Bar-code
* Description (Parts name)
* QTY  (picking)
* “SCH” + Date of print



Master

PIP code – 16 Char

1. Allocation order
2. RF – picking
   1. Assign PickHU ( 1 Pick line 1 PickHU, pre-printed Pick HU)
3. Component label
   1. Scan pick HU
   2. Print PIP Label - allow select # of labels to print. Standard will be 1 orderline 1 label

Eg. Monitor screen 4 pcs into 1 master pack.

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| Orderkey | SKU | Picked Qty | # of label | PIP Code (12 Char) |
|  |  |  |  |  |

\*\* to log the number of label record, insert component pack record and generate case id.

* 1. Label to include Pick HU
  2. For same order line that print multiple labels, the 2nd and subsequence labels will add “\*” to indicate duplicate.

1. Outer packing

For pack all pick hu into single Pack HU , qty is default picked qty

For pack that require spilt to multiple Pack HU, qty will allow user to input and split. -> need to test.

